

NPN Silicon Digital Transistor

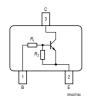
- Switching circuit, inverter, interface circuit driver circuit
- Built in bias resistor (R_1 =10 k Ω , R_2 =47 k Ω)
- BCR135S: Two internally isolated transistors with good matching in one multichip package
- BCR135S: For orientation in reel see package information below
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101

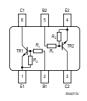




BCR135 BCR135W

BCR135S





| Туре | Marking | Pin Configuration | | | | | Package | |
|---------|---------|-------------------|------|------|------|------|---------|--------|
| BCR135 | WJs | 1=B | 2=E | 3=C | - | - | - | SOT23 |
| BCR135S | WJs | 1=E1 | 2=B1 | 3=C2 | 4=E2 | 5=B2 | 6=C1 | SOT363 |
| BCR135W | WJs | 1=B | 2=E | 3=C | - | - | - | SOT323 |

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Maximum Ratings

| Parameter | Symbol | Value | Unit |
|--|---------------------|---------|------|
| Collector-emitter voltage | $V_{\sf CEO}$ | 50 | V |
| Collector-base voltage | V_{CBO} | 50 | |
| Input forward voltage | V _{i(fwd)} | 40 | |
| Input reverse voltage | V _{i(rev)} | 6 | |
| Collector current | I _C | 100 | mA |
| Total power dissipation | P _{tot} | | mW |
| BCR135, <i>T</i> _S ≤ 102°C | | 200 | |
| BCR135S, <i>T</i> _S ≤ 115°C | | 250 | |
| BCR135W, <i>T</i> _S ≤ 124°C | | 250 | |
| Junction temperature | T_{j} | 150 | °C |
| Storage temperature | T _{stg} | -65 150 | |

Thermal Resistance

| Parameter | Symbol | Value | Unit |
|--|-------------------|--------------|------|
| Junction - soldering point ¹⁾ | R _{thJS} | | K/W |
| BCR135 | | ≤ 240 | |
| BCR135S | | ≤ 140 | |
| BCR135W | | ≤ 105 | |

 $^{^{1}}$ For calculation of R_{thJA} please refer to Application Note AN077 (Thermal Resistance Calculation)



Electrical Characteristics at $T_A = 25$ °C, unless otherwise specified **Symbol Values** Unit **Parameter** min. typ. max. **DC Characteristics** $V_{(BR)CEO}$ ٧ 50 Collector-emitter breakdown voltage $I_{\rm C}$ = 100 μ A, $I_{\rm B}$ = 0 Collector-base breakdown voltage $V_{(BR)CBO}$ 50 $I_{\rm C} = 10 \; \mu {\rm A}, \; I_{\rm E} = 0$ Collector-base cutoff current 100 nΑ I_{CBO} - $V_{\rm CB} = 40 \text{ V}, I_{\rm E} = 0$ 167 μΑ Emitter-base cutoff current *I*_{EBO} $V_{\rm EB} = 6 \text{ V}, I_{\rm C} = 0$ DC current gain¹⁾ 70 h_{FE} $I_{\rm C}$ = 5 mA, $V_{\rm CE}$ = 5 V Collector-emitter saturation voltage¹⁾ V_{CEsat} ٧ 0.3 $I_{\rm C}$ = 10 mA, $I_{\rm B}$ = 0.5 mA Input off voltage $V_{i(off)}$ 0.5 1 $I_{\rm C}$ = 100 μ A, $V_{\rm CE}$ = 5 V $V_{i(on)}$ Input on voltage 0.5 1.4 $I_{\rm C}$ = 2 mA, $V_{\rm CE}$ = 0.3 V R_1 7 13 Input resistor 10 $\mathsf{k}\Omega$ 0.19 R_1/R_2 0.21 0.24 Resistor ratio **AC Characteristics** f_{T} MHz Transition frequency 150 $I_{\rm C}$ = 10 mA, $V_{\rm CE}$ = 5 V, f = 100 MHz рF Collector-base capacitance 3 C_{cb}

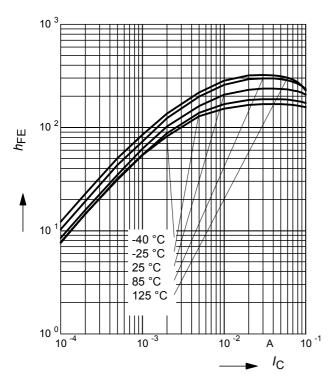
 $V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$

¹Pulse test: t < 300µs; D < 2%



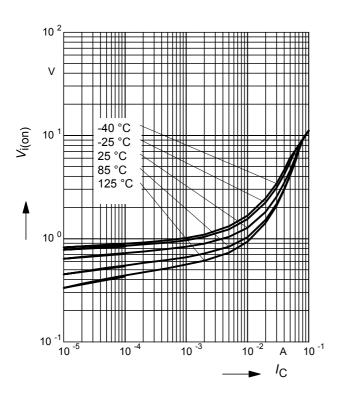
DC current gain $h_{FE} = f(I_C)$

 V_{CE} = 5V (common emitter configuration)



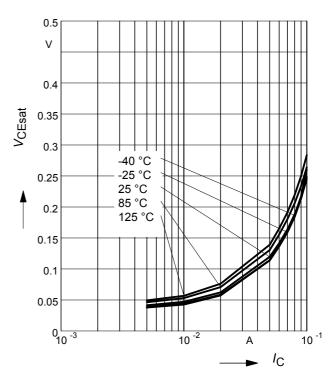
Input on Voltage $Vi_{(On)} = f(I_C)$

 $V_{CE} = 0.3V$ (common emitter configuration)



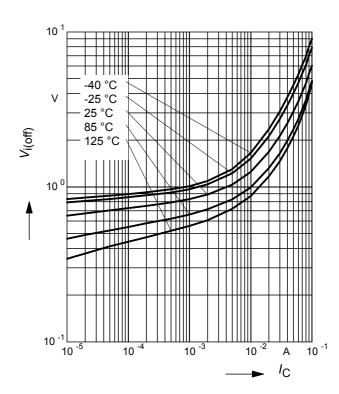
Collector-emitter saturation voltage

 $V_{CEsat} = f(I_{C}), I_{C}/I_{B} = 20$



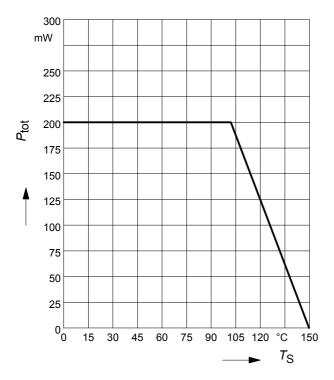
Input off voltage $V_{i(Off)} = f(I_C)$

 V_{CE} = 5V (common emitter configuration)

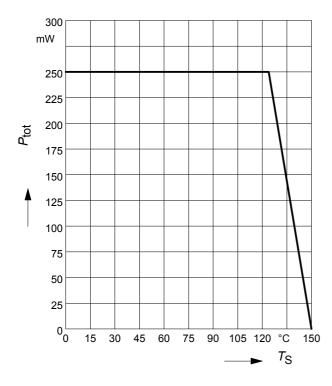




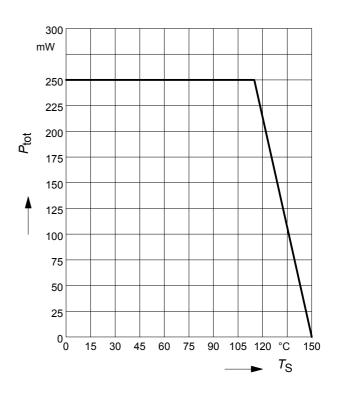
Total power dissipation $P_{tot} = f(T_S)$ BCR135



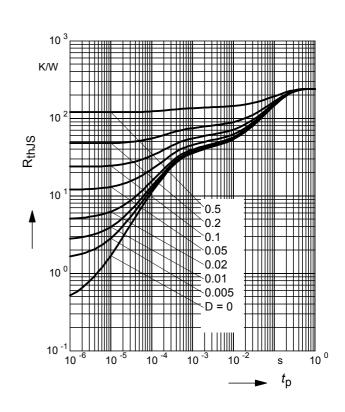
Total power dissipation $P_{tot} = f(T_S)$ BCR135W



Total power dissipation $P_{tot} = f(T_S)$ BCR135S



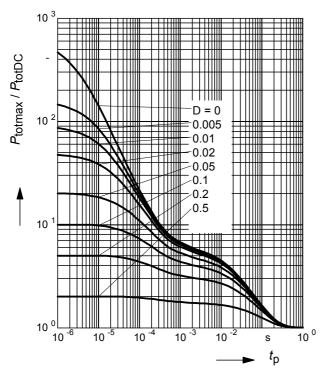
Permissible Pulse Load $R_{thJS} = f(t_p)$ BCR135



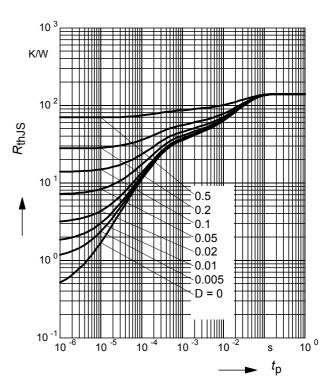


Permissible Pulse Load

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$ BCR135

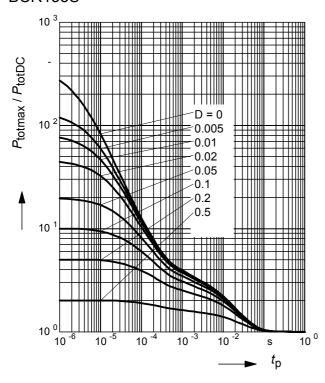


Permissible Puls Load $R_{\rm thJS}$ = f ($t_{\rm p}$) BCR135S

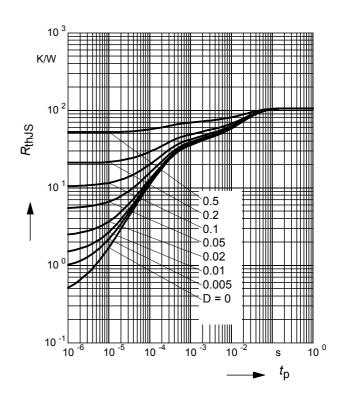


Permissible Pulse Load

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$ BCR135S



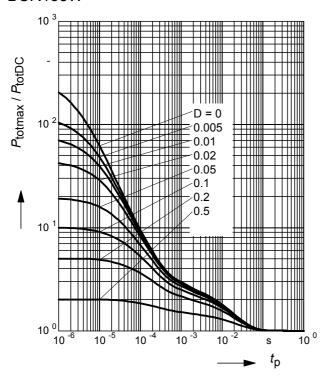
Permissible Puls Load $R_{thJS} = f(t_p)$ BCR135W





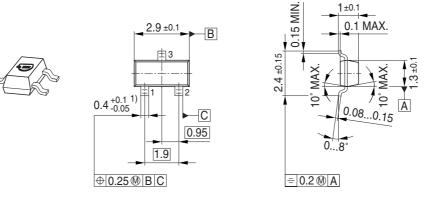
Permissible Pulse Load

 $P_{\text{totmax}}/P_{\text{totDC}} = f(t_{\text{p}})$ BCR135W



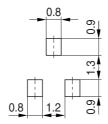


Package Outline

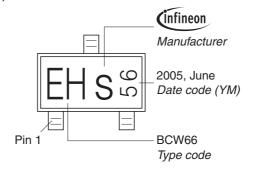


1) Lead width can be 0.6 max. in dambar area

Foot Print

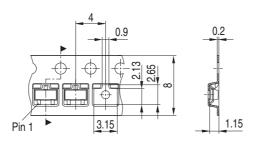


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

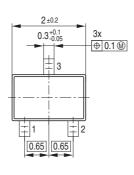


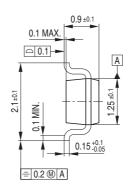
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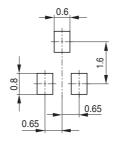
Package Outline



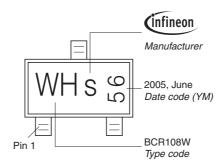




Foot Print

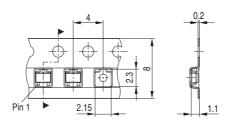


Marking Layout (Example)



Standard Packing

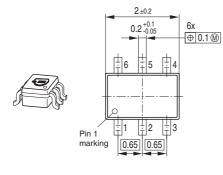
Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

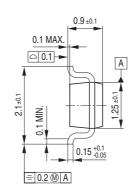


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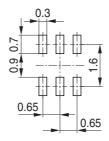


Package Outline



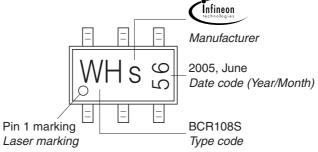


Foot Print



Marking Layout (Example)

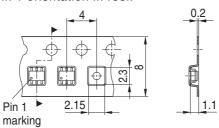
Small variations in positioning of Date code, Type code and Manufacture are possible.



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.





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